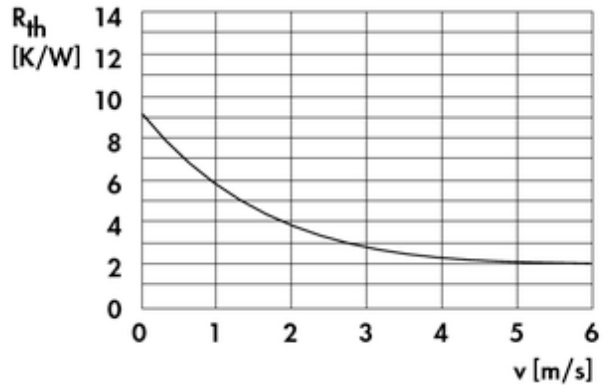
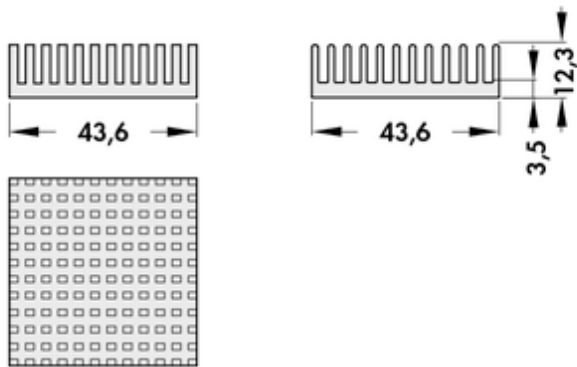
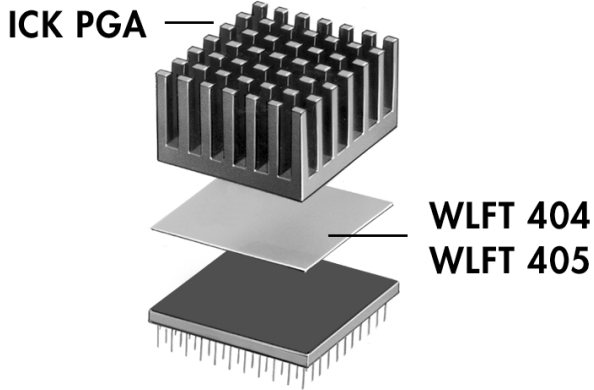


Heatsinks for PGA / **ICK PGA 17 x 17 x 12**



43,6 x 43,6 x 12,3 mm, for IC design PGA and others

Parameters of article ICK PGA 17 x 17 x 12

R_{th} [K/W]	i 9
dissipation loss [W]	i 6.5
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	43.6
height [mm]	12.3
plate thickness [mm]	3.5
length on stock [mm]	43.6
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 43 x 43**

Thermally conductive foil both sides adhesive / **WLFT 405 43 x 43**